N-Channel 40-V (D-S) MOSFET

Key Features:

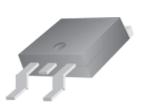
- Low r_{DS(on)} trench technology
- Low thermal impedance
- · Fast switching speed

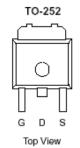
Typical Applications:

- White LED boost converters
- Automotive Systems
- Industrial DC/DC Conversion Circuits

PRODUCT SUMMARY			
V _{DS} (V)	$r_{DS(on)}(m\Omega)$	I _D (A)	
40	12 @ V _{GS} = 10V	53	
40	14 @ V _{GS} = 4.5V	49	







ABSOLUTE MAXIMUM RATINGS (T_A = 25°C UNLESS OTHERWISE NOTED)						
Parameter		Symbol	Limit	Units		
Drain-Source Voltage		V_{DS}	40	V		
Gate-Source Voltage		V_{GS}	±20	V		
Continuous Drain Current ^a	T _A =25°C	I _D	53	Α		
Pulsed Drain Current ^b			200			
Continuous Source Current (Diode Conduction) ^a	Is	44	Α			
Power Dissipation ^a	T _A =25°C	P_{D}	50	W		
Operating Junction and Storage Temperature Range		T_J , T_{stg}	-55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Maximum	Units		
Maximum Junction-to-Ambient ^a	$R_{\theta JA}$	40	°C/W		
Maximum Junction-to-Case	$R_{ heta JC}$	3	C/VV		

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

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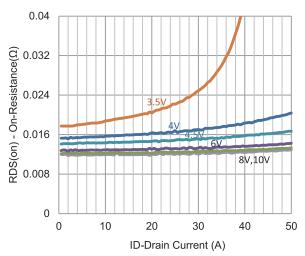
Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static							
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250 \text{ uA}$	1			V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 32 \text{ V}, V_{GS} = 0 \text{ V}$			1	uA	
Zero Gate voltage Drain Current	DSS	$V_{DS} = 32 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			25		
On-State Drain Current	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	100			Α	
Drain-Source On-Resistance	r	$V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$			12		
Drain-Source On-Resistance	r _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 16 \text{ A}$			14	mΩ	
Forward Transconductance	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		20		S	
Diode Forward Voltage	V_{SD}	$I_{S} = 22 \text{ A}, V_{GS} = 0 \text{ V}$		0.97		V	
		Dynamic					
Total Gate Charge	Q_g	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V},$		19		nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.3 \text{ V},$ $I_{D} = 20 \text{ A}$		5.5			
Gate-Drain Charge	Q_{gd}	1 _D – 20 A		10			
Turn-On Delay Time	t _{d(on)}	V = 20 V B = 1.0		8			
Rise Time	t _r	$V_{DS} = 20 \text{ V}, R_{L} = 1 \Omega,$ $I_{D} = 20 \text{ A},$		11		no	
Turn-Off Delay Time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_{GEN} = 6 \Omega$		52		ns	
Fall Time	t _f	• V _{GEN} - 10 V, K _{GEN} - 8 Ω		22			
Input Capacitance	C _{iss}			1826			
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		253		pF	
Reverse Transfer Capacitance	C _{rss}	1		209			

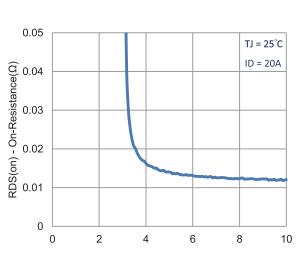
Notes

- a. Pulse test: PW <= 300us duty cycle <= 2%.
- b. Guaranteed by design, not subject to production testing.

Typical Electrical Characteristics

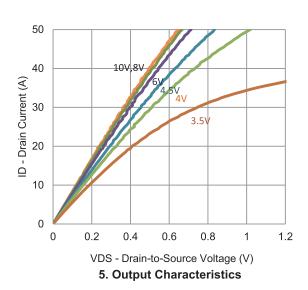


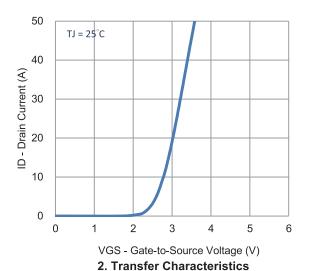
1. On-Resistance vs. Drain Current

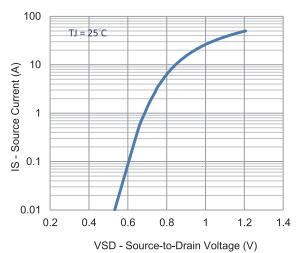


3. On-Resistance vs. Gate-to-Source Voltage

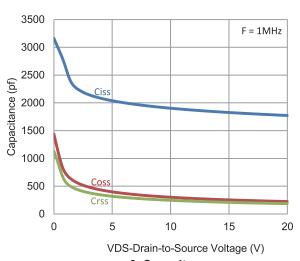
VGS - Gate-to-Source Voltage (V)



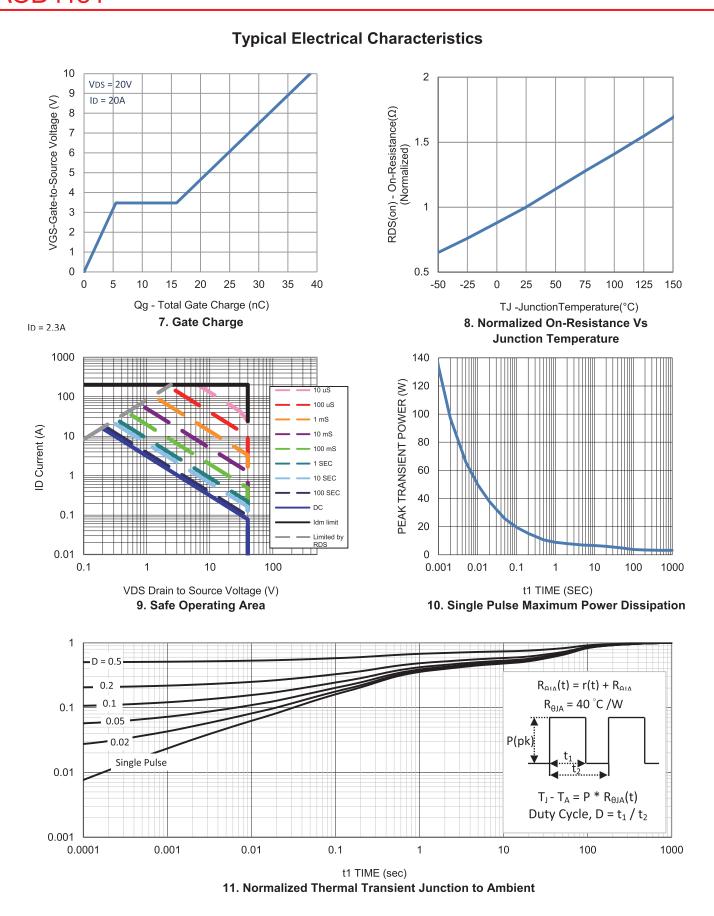




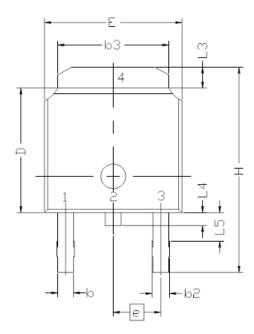
4. Drain-to-Source Forward Voltage

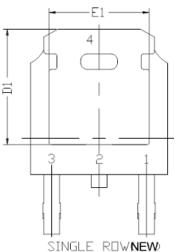


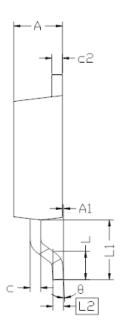
6. Capacitance



Package Information







CVMDDI	DIMENS:		REQMTS		
SYMBOL	MIN	NDM	MAX		
E	6.40	6.60	6.731		
L	1.40	1.52	1.77		
L1	2.743 REF				
L2	0.	.508 BS	C C		
L3	0.89		1.27		
L4	0.64		1.01		
L5					
D	6.00	6.10	6,223		
Н	9.40	10.00	10.40		
b	0.64	0.76	0,88		
b2	0.77	0.84	1.14		
b3	5.21	5.34	5.46		
е	2.	286 BS	C		
Α	2,20	2.30	2.38		
A1	0		0.127		
_	0.45	0.50	0.60		
c2	0.45	0.50	0,58		
D1	5,30				
E1	4.40				
θ	0°		10°		

Note:

- 1. All Dimension Are In mm.
- 2. Package Body Sizes Exclude Mold Flash, Protrusion Or Gate Burrs. Mold Flash, Protrusion Or Gate Burrs Shall Not Exceed 0.10 mm Per Side.
- 3. Package Body Sizes Determined At The Outermost Extremes Of The Plastic Body Exclusive Of Mold Flash, Gate Burrs And Interlead Flash, But Including Any Mismatch Between The Top And Bottom Of The Plastic Body.